

# TCA9846 Ultra Low-Voltage 4-Channel 1MHz Capable I<sup>2</sup>C Switch

## 1 Features

- 1-to-4 bidirectional translating switches with ultra low voltage translation down to 0.65V
- I<sup>2</sup>C bus and SMBus compatible
- Active-low reset input
- 2 address pins, allowing up to 16 TCA9846 devices on the I<sup>2</sup>C bus
- Channel selection through an I<sup>2</sup>C Bus, in any combination
- Power up with all switch channels deselected
- Low R<sub>ON</sub> switches
- Allows voltage-level translation between 0.65V, 0.8, 1.2V, 1.8V, 2.5V, and 3.3V
- No glitch on power up
- Supports hot insertion
- Low standby current
- Operating power-supply voltage range of 1.65V to 3.6V
- 3.6V tolerant inputs
- 0 to 1MHz clock frequency
- Latch-up performance exceeds 100mA per JESD 78, class II
- ESD protection exceeds JESD 22
  - ±2000V human-body model (A114-A)
  - ±500V charged-device model (C101)

## 2 Applications

- Servers
- Routers (telecom switching equipment)
- [Factory automation](#)
- Products with I<sup>2</sup>C target address conflicts (such as multiple, identical temperature sensors)

## 3 Description

The TCA9846 is a quad bidirectional translating switch controlled via the I<sup>2</sup>C bus. The SCL/SDA upstream pair fans out to four downstream pairs, or channels. Any individual SC<sub>n</sub>/SD<sub>n</sub> channel or combination of channels can be selected, determined by the contents of the programmable control register.

An active-low reset ( $\overline{\text{RESET}}$ ) input allows the TCA9846 to recover from a situation in which one of the downstream I<sup>2</sup>C buses is stuck in a low state. Pulling  $\overline{\text{RESET}}$  low resets the I<sup>2</sup>C state machine and causes all the channels to be deselected, as does the internal power-on reset function.

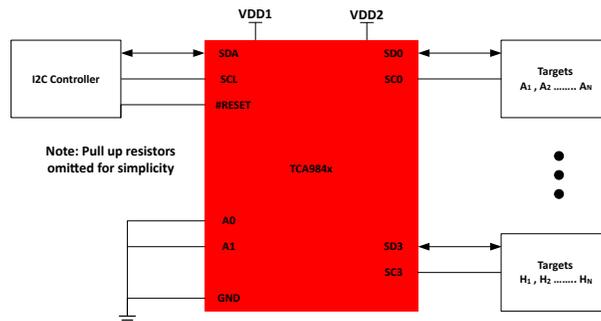
The pass gates of the switches are constructed so that VDD1/VDD2 pins can be used to limit the maximum high voltage, which is passed by the TCA9846. Limiting the maximum high voltage allows the use of different bus voltages on each pair, so that 0.65V, 0.8V, 1.2V, or 1.8V parts can communicate with 3.3V parts, without any additional protection. External pullup resistors pull the bus up to the desired voltage level for each channel. All I/O pins are 3.6V tolerant.

### Package Information

PART NUMBER	PACKAGE (1)	PACKAGE SIZE(2)
TCA9846	PW (TSSOP, 16)	5mm × 6.4mm
	RUM (WQFN, 16)	4mm × 4mm

(1) For more information, see [Section 11](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Simplified Application Diagram



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## 4 Pin Configuration and Functions

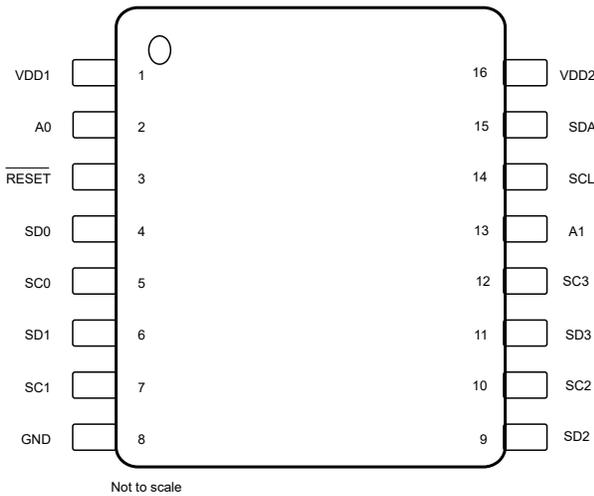


Figure 4-1. PW Package, 16-Pin TSSOP (Top View)

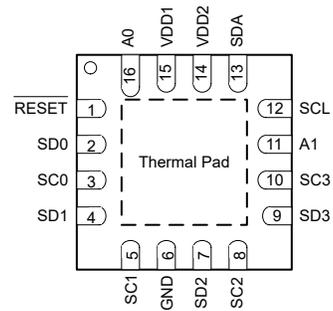


Figure 4-2. RUM Package, 16-Pin WQFN (Top View)

Table 4-1. Pin Functions

NAME	PIN		TYPE	DESCRIPTION
	TSSOP (PW)	WQFN (RUM)		
A0	2	16	I	Address input 0. Connect directly to V <sub>DD2</sub> or ground
A1	13	11	I	Address input 1. Connect directly to V <sub>DD2</sub> or ground
VDD1	1	15	Power	Logic Level Power Supply(VCC)
VDD2	16	14	Power	Core Logic Power Supply(VCC)
RESET	3	1	I	Active-low reset input. Connect to V <sub>DD2</sub> or V <sub>DPUM</sub> <sup>(1)</sup> through a pull-up resistor, if not used
SD0	4	2	I/O	Serial data 0. Connect to V <sub>DPU0</sub> <sup>(1)</sup> through a pull-up resistor
SC0	5	3	I/O	Serial clock 0. Connect to V <sub>DPU0</sub> <sup>(1)</sup> through a pull-up resistor
SD1	6	4	I/O	Serial data 1. Connect to V <sub>DPU1</sub> <sup>(1)</sup> through a pull-up resistor
SC1	7	5	I/O	Serial clock 1. Connect to V <sub>DPU1</sub> <sup>(1)</sup> through a pull-up resistor
SD2	8	7	I/O	Serial data 2. Connect to V <sub>DPU2</sub> <sup>(1)</sup> through a pull-up resistor
SC2	9	8	I/O	Serial clock 2. Connect to V <sub>DPU2</sub> <sup>(1)</sup> through a pull-up resistor
SD3	10	9	I/O	Serial data 3. Connect to V <sub>DPU3</sub> <sup>(1)</sup> through a pull-up resistor
SC3	11	10	I/O	Serial clock 3. Connect to V <sub>DPU3</sub> <sup>(1)</sup> through a pull-up resistor
SCL	13	12	I/O	Serial clock bus. Connect to V <sub>DPUM</sub> <sup>(1)</sup> through a pull-up resistor
SDA	14	13	I/O	Serial data bus. Connect to V <sub>DPUM</sub> <sup>(1)</sup> through a pull-up resistor
GND	8	6	-	Supply Ground

(1) V<sub>DPUX</sub> is the pull-up reference voltage for the associated data line. V<sub>DPUM</sub> is the controller I<sup>2</sup>C reference voltage and V<sub>DPU0</sub>-V<sub>DPU3</sub> are the target channel reference voltages.

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	-0.5	4	V
V <sub>I</sub>	Input voltage <sup>(2)</sup>	-0.5	4	V
I <sub>I</sub>	Input current	-20	20	mA
I <sub>O</sub>	Output current	-25	25	mA
I <sub>CC</sub>	Supply current	-100	100	mA
T <sub>amb</sub>	Ambient Temperature	-40	125	°C
T <sub>stg</sub>	Storage temperature	-65	150	°C

- Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- The input negative-voltage and output voltage ratings can be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 <sup>(2)</sup>	±500	

- JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

T<sub>amb</sub> = -40°C to 125°C; unless otherwise specified

			MIN	TYP	MAX	UNIT
VDD1	Supply voltage 1		0.65		3.6	V
VDD2	Supply voltage 2		1.65		3.6	V
IDD (VDD2)	Supply Current on VDD2	VDD1 = 3.6; VDD2 = 3.6; SC0-7 and SD0-7 is not connected; RESET = VDD1; A0=A1=SCL; continuous register read/write				
IDD (VDD2)	Supply Current on VDD2	SCL = 0kHz		5	12	µA
IDD (VDD2)	Supply Current on VDD2	SCL = 100kHz		8	20	µA
IDD (VDD2)	Supply Current on VDD2	SCL = 1000kHz		65	150	µA
IDD (VDD1)	Supply Current on VDD1	VDD1 = 3.6; VDD2 = 3.6; SC0-7 and SD0-7 is not connected; RESET = VDD1; A0=A1=SCL; continuous register read/write				
		SCL = 0kHz	-5	-2	+2	µA
		SCL = 100kHz		5	15	µA
		SCL = 1000kHz		45	100	µA
VPOR	Power-On Reset Voltage			1.2	1.5	V
T <sub>A</sub>	Operating free-air temperature		-40		125	°C

## 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TCA984x		UNIT
		PW (TSSOP)	RUM (WQFN)	
		16 PINS	16 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	TBD	TBD	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	TBD	TBD	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	TBD	TBD	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	TBD	TBD	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	TBD	TBD	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	TBD	TBD	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

## 5.5 Electrical Characteristics (Global)

 $T_A = 25^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$T_A$	MIN	TYP	MAX	UNIT
<b>Recommended Supply Sequencing and Ramp Rates</b>							
$(dV/dt)_f$	fall rate of change of voltage		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	0.1		2000	ms
$(dV/dt)_r$	rise rate of change of voltage		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	0.1		2000	ms
$t_{d(\text{rst})}$	reset delay time		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	10			us
$\Delta V_{DD(\text{gl})}$	glitch supply voltage difference		$-40^\circ\text{C}$ to $+125^\circ\text{C}$			1	V
$t_{w(\text{gl})VDD}$	supply voltage glitch pulse width		$-40^\circ\text{C}$ to $+125^\circ\text{C}$			10	us
$V_{\text{POR}(\text{trip})}$	power-on reset trip voltage	Falling VDD2	$-40^\circ\text{C}$ to $+125^\circ\text{C}$	0.7			V
		Rising VDD2	$-40^\circ\text{C}$ to $+125^\circ\text{C}$			1.5	V
<b>SCL/SDA</b>							
$V_{\text{IH}}$	Logic voltage high		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	$0.7V_{\text{DD1}}$		3.6	V
$V_{\text{IL}}$	Logic voltage low		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	-0.5	$+0.3V_{\text{D1}}$		V
$I_{\text{OL}}$	LOW-level output current	$V_{\text{OL}} = 0.4\text{V}$	$-40^\circ\text{C}$ to $+125^\circ\text{C}$	20			mA
$I_{\text{IL}}$	Input leakage current	$V_{\text{I}} = V_{\text{DD}}$ or 0	$-40^\circ\text{C}$ to $+125^\circ\text{C}$	-1		1	uA
$C_{\text{IN}}$	Logic input capacitance	$V_{\text{I}} = V_{\text{SS}}$ ; all channels disabled	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		10	12	pF
<b>SEL Inputs: A0-A1, RESET</b>							
$V_{\text{IH}}$	Logic voltage high		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	$0.7V_{\text{DD1}}$		3.6	V
$V_{\text{IL}}$	Logic voltage low		$-40^\circ\text{C}$ to $+125^\circ\text{C}$	-0.5	$+0.3V_{\text{D1}}$		V
$I_{\text{IL}}$	Input leakage current	$V_{\text{I}} = V_{\text{DD}}$ or 0	$-40^\circ\text{C}$ to $+125^\circ\text{C}$	-1		1	uA
$C_{\text{IN}}$	Logic input capacitance	$V_{\text{I}} = V_{\text{SS}}$ ; all channels disabled	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		2	4	pF
<b>Pass Gate</b>							
$R_{\text{ON}}$	ON-state resistance	$V_{\text{DD1}} = 0.8\text{V}$ ; $V_{\text{DD2}} \geq 1.65\text{V}$ ; $V_{\text{i}(\text{sw})} = 0.16\text{V}$ ; $I_{\text{O}} = 3\text{mA}$	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		10	24	$\Omega$
		$V_{\text{DD1}} = 0.65\text{V}$ ; $V_{\text{DD2}} \geq 1.65\text{V}$ ; $V_{\text{i}(\text{sw})} = 0.16\text{V}$ ; $I_{\text{O}} = 3\text{mA}$	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		10	24	$\Omega$
		$V_{\text{DD1}} = 1.2\text{V}$ ; $V_{\text{DD2}} \geq 1.8\text{V}$ ; $V_{\text{i}(\text{sw})} = 0.24\text{V}$ ; $I_{\text{O}} = 6\text{mA}$	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		7	18	$\Omega$
		$V_{\text{DD1}} > 2\text{V}$ ; $V_{\text{DD2}} \geq 2.5\text{V}$ ; $V_{\text{i}(\text{sw})} = 0.4\text{V}$ ; $I_{\text{O}} = 20\text{mA}$	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		5	12	$\Omega$
$I_{\text{O}(\text{sw})}$	Switch Output Current	$V_{\text{DD2}} = 1.65\text{V}$ to $3.6\text{V}$ ; $V_{\text{i}(\text{sw})} = V_{\text{DD1}}$ to $3.6\text{V}$ ; $V_{\text{o}(\text{sw})} = V_{\text{DD1}}$ to $3.6\text{V}$	$-40^\circ\text{C}$ to $+125^\circ\text{C}$	0		100	uA
IL	Leakage current	$V_{\text{I}} = V_{\text{DD}}$ or GND	$-40^\circ\text{C}$ to $+125^\circ\text{C}$	-1		+1.5	uA
COFF	Input/Output Capacitance	$V_{\text{I}} = \text{GND}$ ; all switches disabled	$-40^\circ\text{C}$ to $+125^\circ\text{C}$		3	5	pF

## 5.6 I<sup>2</sup>C Interface Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
<b>STANDARD MODE</b>					
f <sub>scl</sub>	I <sup>2</sup> C clock frequency	0	100	kHz	
t <sub>sch</sub>	I <sup>2</sup> C clock high time	4		µs	
t <sub>scl</sub>	I <sup>2</sup> C clock low time	4.7		µs	
t <sub>sp</sub>	I <sup>2</sup> C spike time	50		ns	
t <sub>sds</sub>	I <sup>2</sup> C serial-data setup time	250		ns	
t <sub>sdh</sub>	I <sup>2</sup> C serial-data hold time	0 <sup>(1)</sup>		µs	
t <sub>icr</sub>	I <sup>2</sup> C input rise time		1000	ns	
t <sub>icf</sub>	I <sup>2</sup> C input fall time		300	ns	
t <sub>ocf</sub>	I <sup>2</sup> C output (SDn) fall time (10pF to 400pF bus)		300	ns	
t <sub>buf</sub>	I <sup>2</sup> C bus free time between stop and start	4.7		µs	
t <sub>sts</sub>	I <sup>2</sup> C start or repeated start condition setup	4.7		µs	
t <sub>sth</sub>	I <sup>2</sup> C start or repeated start condition hold	4		µs	
t <sub>sps</sub>	I <sup>2</sup> C stop condition setup	4		µs	
t <sub>vdL(Data)</sub>	Valid-data time (high to low) <sup>(2)</sup>	SCL low to SDA output low valid	1	µs	
t <sub>vdH(Data)</sub>	Valid-data time (low to high) <sup>(2)</sup>	SCL low to SDA output high valid	0.6	µs	
t <sub>vd(ack)</sub>	Valid-data time of ACK condition	ACK signal from SCL low to SDA output low	1	µs	
C <sub>b</sub>	I <sup>2</sup> C bus capacitive load		400	pF	
<b>FAST MODE</b>					
f <sub>scl</sub>	I <sup>2</sup> C clock frequency	0	400	kHz	
t <sub>sch</sub>	I <sup>2</sup> C clock high time	0.6		µs	
t <sub>scl</sub>	I <sup>2</sup> C clock low time	1.3		µs	
t <sub>sp</sub>	I <sup>2</sup> C spike time	50		ns	
t <sub>sds</sub>	I <sup>2</sup> C serial-data setup time	100		ns	
t <sub>sdh</sub>	I <sup>2</sup> C serial-data hold time	0 <sup>(1)</sup>		µs	
t <sub>icr</sub>	I <sup>2</sup> C input rise time	20 + 0.1C <sub>b</sub> <sup>(3)</sup>	300	ns	
t <sub>icf</sub>	I <sup>2</sup> C input fall time	20 + 0.1C <sub>b</sub> <sup>(3)</sup>	300	ns	
t <sub>ocf</sub>	I <sup>2</sup> C output (SDn) fall time (10pF to 400pF bus)	20 + 0.1C <sub>b</sub> <sup>(3)</sup>	300	ns	
t <sub>buf</sub>	I <sup>2</sup> C bus free time between stop and start	1.3		µs	
t <sub>sts</sub>	I <sup>2</sup> C start or repeated start condition setup	0.6		µs	
t <sub>sth</sub>	I <sup>2</sup> C start or repeated start condition hold	0.6		µs	
t <sub>sps</sub>	I <sup>2</sup> C stop condition setup	0.6		µs	
t <sub>vdL(Data)</sub>	Valid-data time (high to low) <sup>(2)</sup>	SCL low to SDA output low valid	1	µs	
t <sub>vdH(Data)</sub>	Valid-data time (low to high) <sup>(2)</sup>	SCL low to SDA output high valid	0.6	µs	
t <sub>vd(ack)</sub>	Valid-data time of ACK condition	ACK signal from SCL low to SDA output low	1	µs	
C <sub>b</sub>	I <sup>2</sup> C bus capacitive load		400	pF	
<b>FAST MODE PLUS</b>					
f <sub>scl</sub>	I <sup>2</sup> C clock frequency	I <sup>2</sup> C clock frequency	0	1000	kHz
t <sub>sch</sub>	I <sup>2</sup> C clock high time	I <sup>2</sup> C clock high time	0.26		µs
t <sub>scl</sub>	I <sup>2</sup> C clock low time	I <sup>2</sup> C clock low time	0.5		µs
t <sub>sp</sub>	I <sup>2</sup> C spike time	I <sup>2</sup> C spike time		50	ns
t <sub>sds</sub>	I <sup>2</sup> C serial-data setup time	I <sup>2</sup> C serial-data setup time	100		ns
t <sub>sdh</sub>	I <sup>2</sup> C serial-data hold time	I <sup>2</sup> C serial-data hold time	0 <sup>(1)</sup>		µs
t <sub>icr</sub>	I <sup>2</sup> C input rise time	I <sup>2</sup> C input rise time		120	ns
t <sub>icf</sub>	I <sup>2</sup> C input fall time	I <sup>2</sup> C input fall time	20 × (VDD / 5.5V) <sup>(3)</sup>	120	ns
t <sub>buf</sub>	I <sup>2</sup> C bus free time between stop and start	I <sup>2</sup> C bus free time between stop and start	0.5		µs

## 5.6 I<sup>2</sup>C Interface Timing Requirements (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			MIN	MAX	UNIT
t <sub>sts</sub>	I <sup>2</sup> C start or repeated start condition setup	I <sup>2</sup> C start or repeated start condition setup	0.26		μs
t <sub>sth</sub>	I <sup>2</sup> C start or repeated start condition hold	I <sup>2</sup> C start or repeated start condition hold	0.26		μs
t <sub>sps</sub>	I <sup>2</sup> C stop condition setup	I <sup>2</sup> C stop condition setup	0.6		μs
t <sub>vdL(Data)</sub>	Valid-data time (high to low) <sup>(2)</sup>	SCL low to SDA output low valid		0.45	μs
t <sub>vdH(Data)</sub>	Valid-data time (low to high) <sup>(2)</sup>	SCL low to SDA output high valid		0.45	μs
t <sub>vd(ack)</sub>	Valid-data time of ACK condition	ACK signal from SCL low to SDA output low		0.45	μs
C <sub>b</sub>	I <sup>2</sup> C bus capacitive load	I <sup>2</sup> C bus capacitive load		550	pF

- (1) A device internally must provide a hold time of at least 300ns for the SDA signal (referred to the V<sub>IH</sub> min of the SCL signal), to bridge the undefined region of the falling edge of SCL.
- (2) Data taken using a 1kΩ pullup resistor and 50pF load
- (3) C<sub>b</sub> = total bus capacitance of one bus line in pF

## 5.7 Reset Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			MIN	MAX	UNIT
t <sub>wrs(L)</sub>	Low-level reset time		100		ns
t <sub>REC(STA)</sub>	Recovery time from RESET to start		0		ns

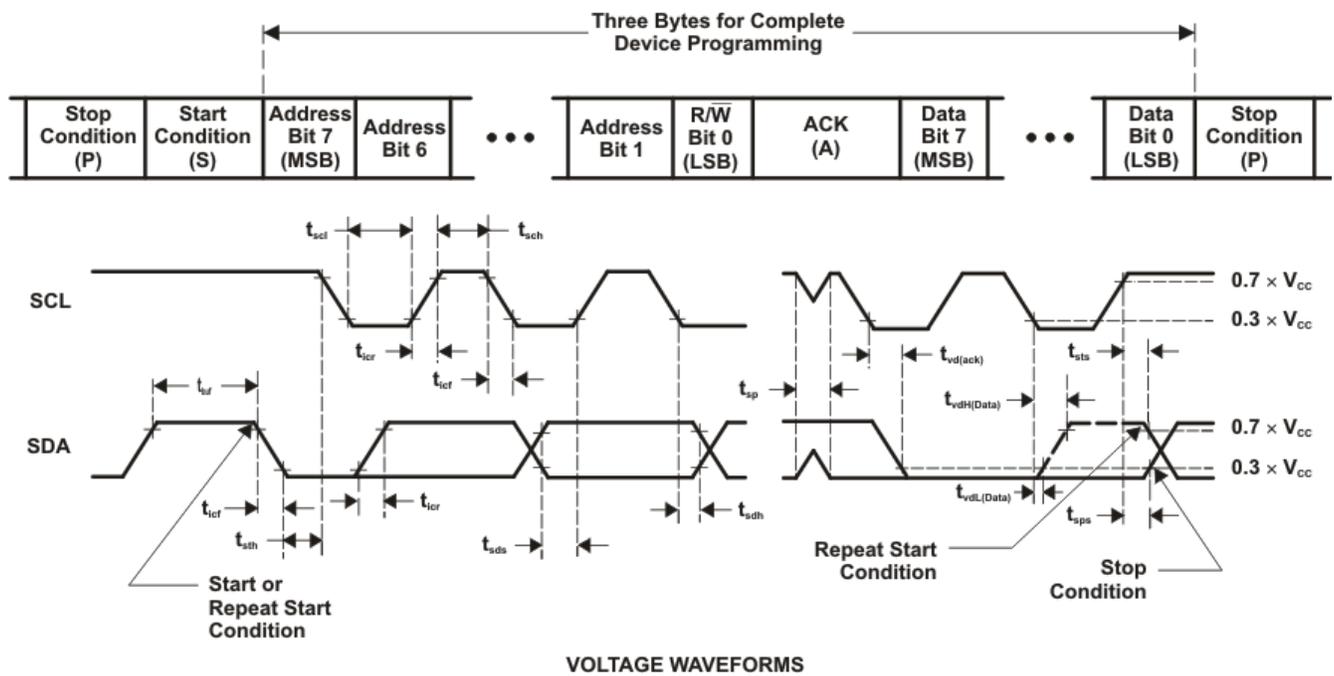
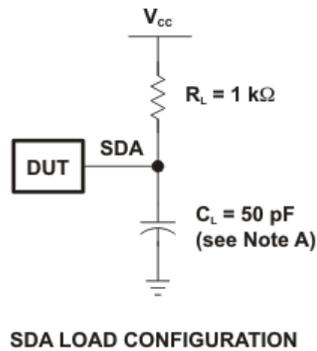
## 5.8 Switching Characteristics

over recommended operating free-air temperature range, C<sub>L</sub> ≤ 100pF (unless otherwise noted)

PARAMETER			FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t <sub>pd</sub> <sup>(1)</sup>	Propagation delay time	R <sub>ON</sub> = 20 Ω, C <sub>L</sub> = 50pF	SDA or SCL	SDn or SCn		1	ns
t <sub>rst</sub> <sup>(2)</sup>	RESET time (SDA clear)		RESET	SDA	500		ns

- (1) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- (2) t<sub>rst</sub> is the propagation delay measured from the time the RESET pin is first asserted low to the time the SDA pin is asserted high, signaling a stop condition. t<sub>rst</sub> must be a minimum of t<sub>WL</sub>.

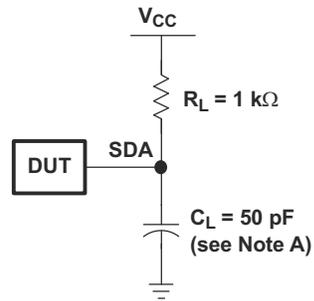
## 6 Parameter Measurement Information



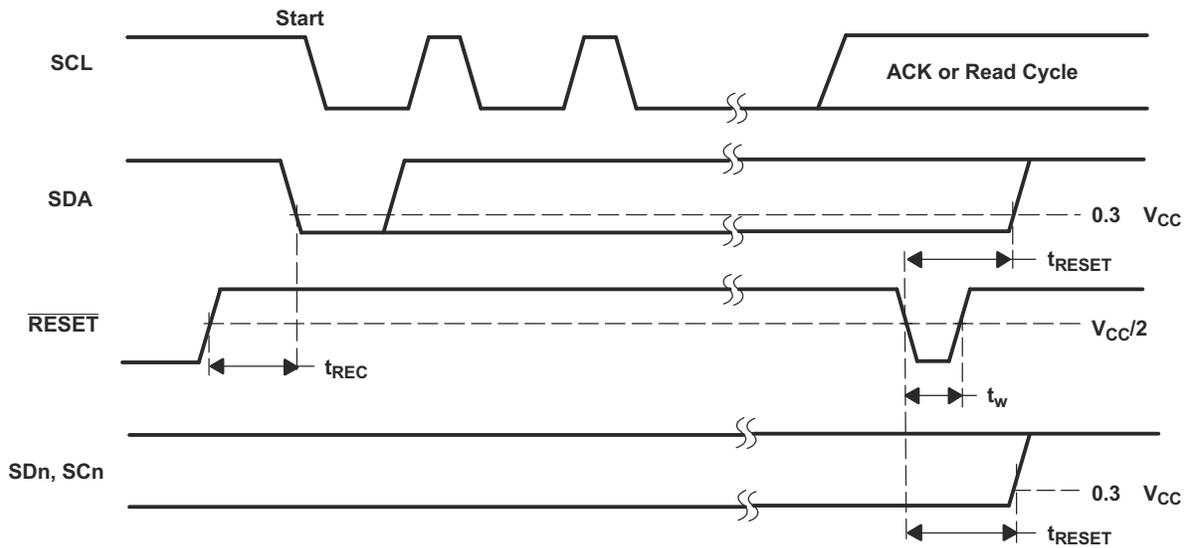
BYTE	DESCRIPTION
1	I <sup>2</sup> C address
2, 3	P-port data

- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10\text{MHz}$ ,  $Z_O = 50\Omega$ ,  $t_r/t_f \leq 30\text{ns}$ .
- C. Not all parameters and waveforms are applicable to all devices.

**Figure 6-1. I<sup>2</sup>C Load Circuit and Voltage Waveforms**



SDA LOAD CONFIGURATION



- $C_L$  includes probe and jig capacitance.
- All inputs are supplied by generators having the following characteristics:  $PRR \leq 10\text{MHz}$ ,  $Z_O = 50\Omega$ ,  $t_r/t_f \leq 30\text{ns}$ .
- I/Os are configured as inputs.
- Not all parameters and waveforms are applicable to all devices.

Figure 6-2. Reset Load Circuit and Voltage Waveforms

## 7 Detailed Description

### 7.1 Overview

The TCA9846 is a 4-channel, bidirectional translating I2C switch. The controller SCL/SDA signal pair is directed to four channels of target devices, SC0/SD0-SC3/SD3. Any individual downstream channel can be selected as well as any combination of the four channels.

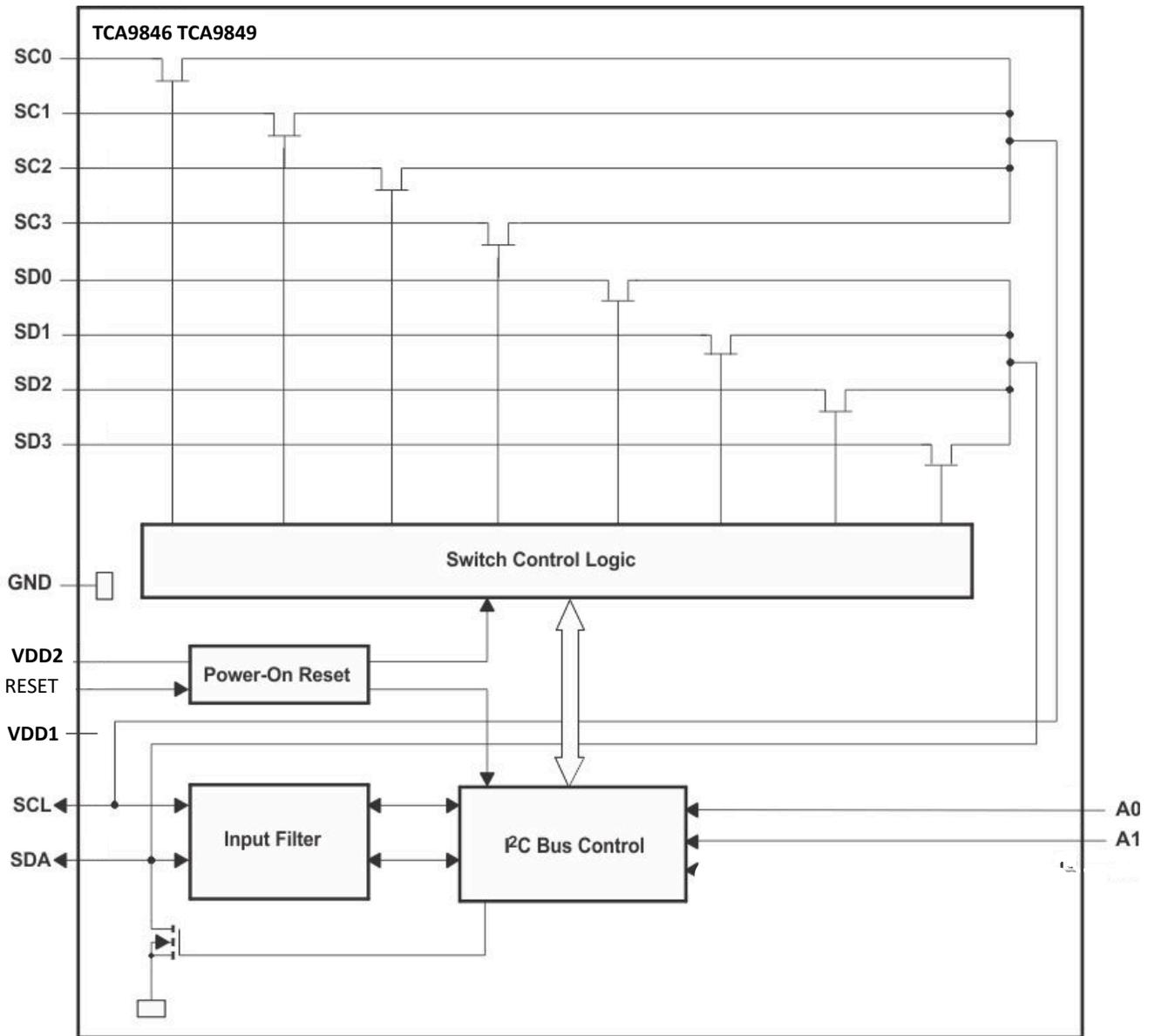
The device offers an active-low  $\overline{\text{RESET}}$  input which resets the state machine and allows the TCA9846 to recover if one of the downstream I2C buses get stuck in a low state. The state machine of the device can also be reset by cycling the power supply, VCC, also known as a power-on reset (POR). Both the  $\overline{\text{RESET}}$  function and a POR cause all channels to be deselected.

The connections of the I2C data path are controlled by the same I2C controller device that is switched to communicate with multiple I2C targets. After the successful acknowledgment of the target address (hardware selectable by A0 and A1 pins), a single 8-bit control register is written to or read from to determine the selected channels.

The TCA9846 can also be used for voltage translation, allowing the use of different bus voltages on each SCn/SDn pair such that 0.65V, 0.8V, 1.2V, or 1.8V parts can communicate with 3.3V parts. This action is achieved by using external pullup resistors to pull the bus up to the desired voltage for the controller and each target channel.

## 7.2 Functional Block Diagram

ADVANCE INFORMATION



## 7.3 Feature Description

The TCA9846 is an 4-channel, bidirectional translating switch for I<sup>2</sup>C buses that supports Standard-Mode (100kHz), Fast-Mode (400kHz), and Fast-Mode-Plus (1Mhz) operation. The TCA9846 features I<sup>2</sup>C control using a single 8-bit control register in which each bit controls the enabling and disabling of one of the corresponding 4 switch channels for I<sup>2</sup>C data flow. Depending on the application, voltage translation of the I<sup>2</sup>C bus can also be achieved using the TCA9846 to allow 0.65V, 0.8V, 1.2V, or 1.8V parts to communicate with 3.3V parts. Additionally, in the event that communication on the I<sup>2</sup>C bus enters a fault state, the TCA9846 can be reset to resume normal operation using the  $\overline{\text{RESET}}$  pin feature or by a power-on reset which results from cycling power to the device.

## 7.4 Device Functional Modes

### 7.4.1 $\overline{\text{RESET}}$ Input

The  $\overline{\text{RESET}}$  input is an active-low signal that can be used to recover from a bus-fault condition. When this signal is asserted low for a minimum of  $t_{WL}$ , the TCA9846 resets the registers and I<sup>2</sup>C state machine and deselects all channels. The  $\overline{\text{RESET}}$  input must be connected to V<sub>CC</sub> through a pullup resistor.

### 7.4.2 Power-On Reset

When power is applied to the VCC pin, an internal power-on reset holds the TCA9846 in a reset condition until V<sub>CC</sub> has reached V<sub>PORR</sub>. At this point, the reset condition is released, and the TCA9846 registers and I<sup>2</sup>C state machine are initialized to the default states, all zeroes, causing all the channels to be deselected. Thereafter, V<sub>CC</sub> must be lowered below V<sub>PORF</sub> to reset the device.

## 7.5 Programming

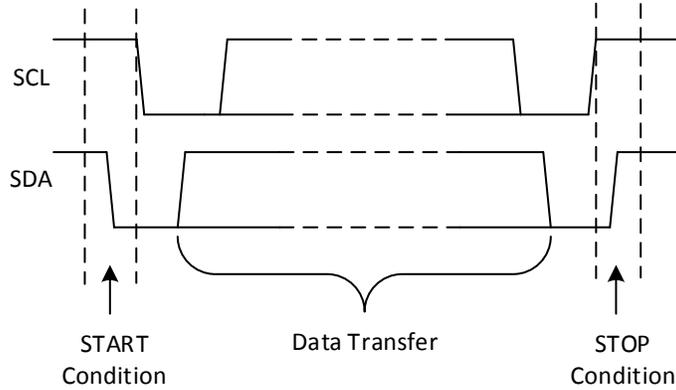
### 7.5.1 I<sup>2</sup>C Interface

The TCA9846 has a standard bidirectional I<sup>2</sup>C interface that is controlled by a controller device to be configured or read the status of this device. Each target on the I<sup>2</sup>C bus has a specific device address to differentiate between other target devices that are on the same I<sup>2</sup>C bus. Many target devices require configuration upon startup to set the behavior of the device. This is typically done when the controller accesses internal register maps of the target, which have unique register addresses. A device can have one or multiple registers where data is stored, written, or read.

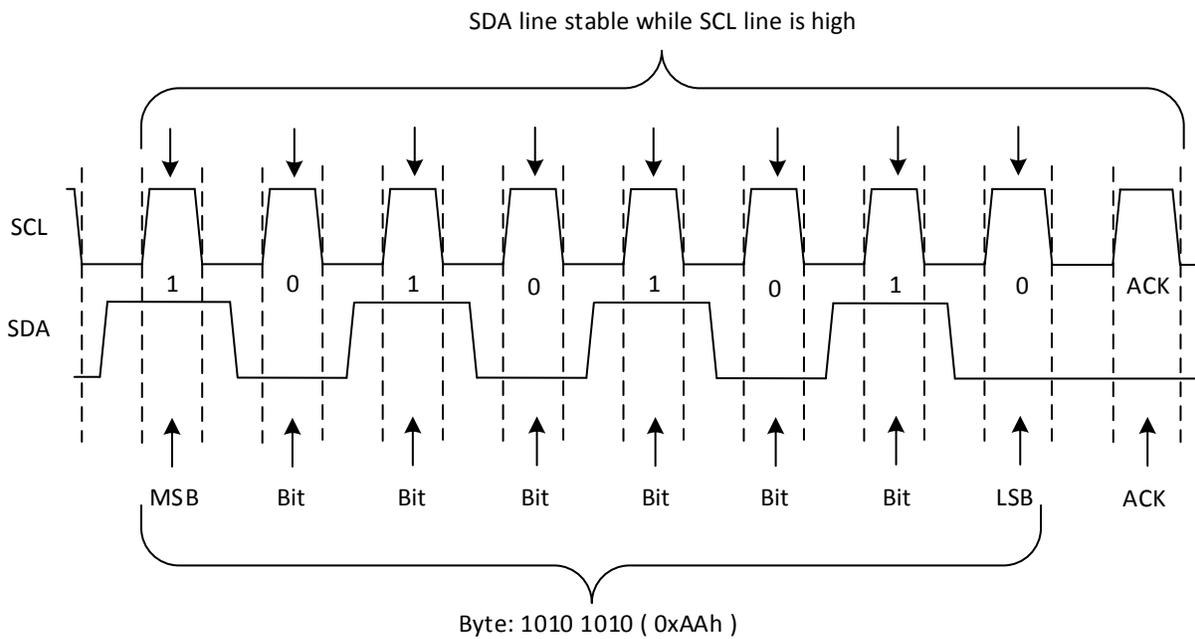
The physical I<sup>2</sup>C interface consists of the serial clock (SCL) and serial data (SDA) lines. Both SDA and SCL lines must be connected to V<sub>CC</sub> through a pull-up resistor. The size of the pull-up resistor is determined by the amount of capacitance on the I<sup>2</sup>C lines. (For further details, see the [I<sup>2</sup>C Pull-up Resistor Calculation](#) application note. Data transfer can only be initiated when the bus is idle. A bus is considered idle if both SDA and SCL lines are high after a STOP condition (See [Figure 7-1](#) and [Figure 7-2](#)).

The following is the general procedure for a controller to access a target device:

1. If a controller wants to send data to a target:
  - Controller-transmitter sends a START condition and addresses the target-receiver.
  - Controller-transmitter sends data to target-receiver.
  - Controller-transmitter terminates the transfer with a STOP condition.
2. If a controller wants to receive or read data from a target:
  - Controller-receiver sends a START condition and addresses the target-transmitter.
  - Controller-receiver sends the requested register to read to target-transmitter.
  - Controller-receiver receives data from the target-transmitter.
  - Controller-receiver terminates the transfer with a STOP condition.



**Figure 7-1. Definition of Start and Stop Conditions**



**Figure 7-2. Bit Transfer**

ADVANCE INFORMATION

### 7.5.2 Device Address

The last bit of the target address defines the operation (read or write) to be performed. When it is high (1), a read is selected, while a low (0) selects a write operation.

Table 7-1 shows the TCA9846 address reference.

**Table 7-1. Address Reference**

INPUTS		I <sup>2</sup> C BUS TARGETADDRESS
A1	A0	
L	SCL	0xE0h (hexadecimal)
L	L	0xE2h (hexadecimal)
L	SDA	0xE4h (hexadecimal)
L:	H	0xE6h (hexadecimal)
H	SCL	0xE8h (hexadecimal)
H	L	0xEAh (hexadecimal)
H	SDA	0xECh (hexadecimal)
H	H	0xEEh (hexadecimal)
SCL	SCL	0xB0h (hexadecimal)
SCL	L	0xB2h (hexadecimal)
SCL	SDA	0xB4h (hexadecimal)
SCL	H	0xB6h (hexadecimal)
SDA	SCL	0xB8h (hexadecimal)
SDA	L	0xBAh (hexadecimal)
SDA	SDA	0xBCh (hexadecimal)
SDA	1	0xBEh (hexadecimal)

### 7.5.3 Bus Transactions

Data must be sent to and received from the target devices, and this is accomplished by reading from or writing to registers in the target device.

Registers are locations in the memory of the target which contain information, whether configuration information or some sampled data to send back to the controller. The controller must write information to these registers to instruct the target device to perform a task.

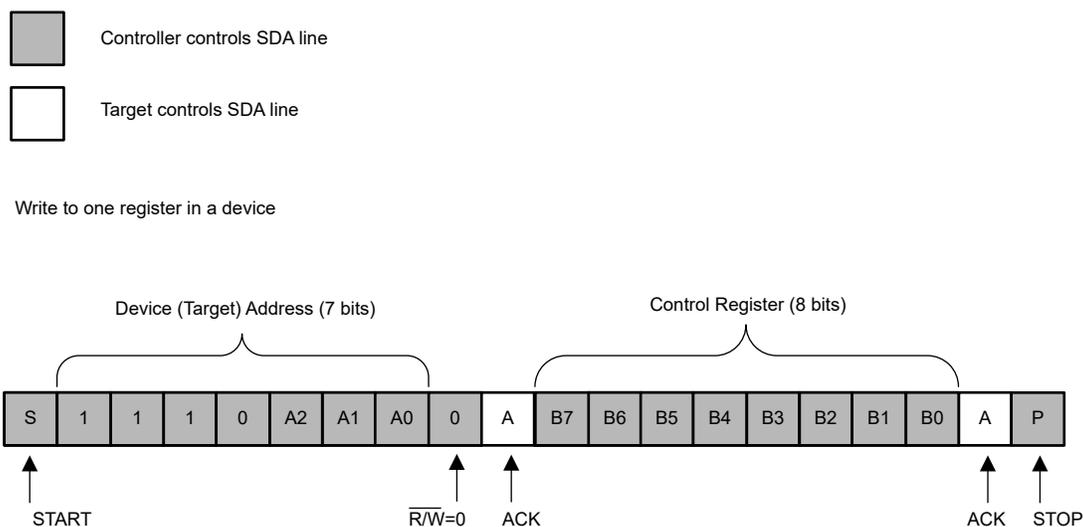
While having registers in I<sup>2</sup>C targets is common, note that not all target devices have registers. Some devices are simple and contain only 1 register, which can be written to directly by sending the register data immediately after the target address, instead of addressing a register. The TCA9846 is example of a single-register device, which is controlled through I<sup>2</sup>C commands. Because it has 1 bit to enable or disable a channel, there is only 1 register needed, and the controller merely writes the register data after the target address, skipping the register number.

#### 7.5.3.1 Writes

To write on the I<sup>2</sup>C bus, the controller sends a START condition on the bus with the address of the target, as well as the last bit (the R/  $\bar{W}$  bit) set to 0, which signifies a write. The target acknowledges, letting the controller know the target is ready. After this action, the controller starts sending the control register data to the target until the controller has sent all the data necessary (which is sometimes only a single byte), and the controller terminates the transmission with a STOP condition.

There is no limit to the number of bytes sent, but the last byte sent is what is in the register.

Figure 7-3 shows an example of writing a single byte to a target register.



**Figure 7-3. Write to Register**

#### 7.5.3.2 Reads

Reading from a target is very similar to writing, but the controller sends a START condition, followed by the target address with the R/  $\bar{W}$  bit set to 1 (signifying a read). The target acknowledges the read request, and the controller releases the SDA bus but continues supplying the clock to the target. During this part of the transaction, the controller becomes the controller-receiver, and the target becomes the target-transmitter.

The controller continues to send out the clock pulses, but releases the SDA line so that the target can transmit data. At the end of every byte of data, the controller sends an ACK to the target, letting the target know that the controller is ready for more data. After the controller has received the number of bytes the controller is expecting, the controller sends a NACK, signaling to the target to halt communications and release the bus. The controller follows this up with a STOP condition.

Figure 7-4 shows an example of reading a single byte from a target register.

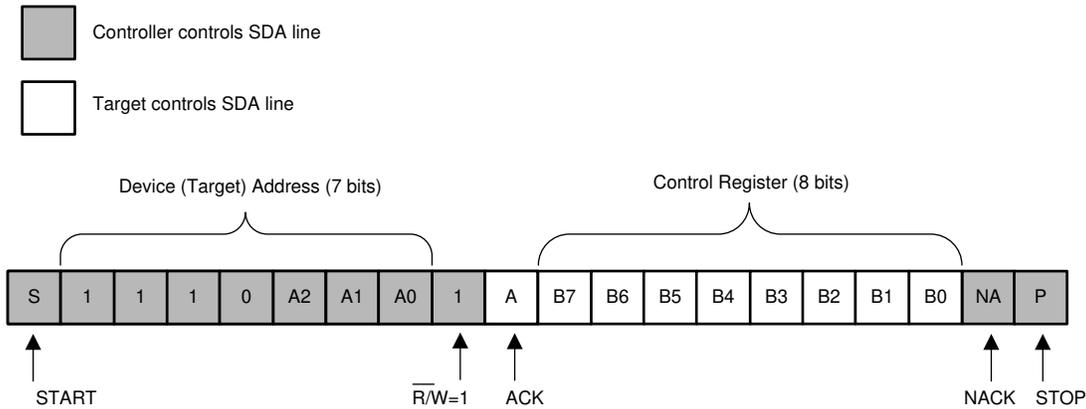


Figure 7-4. Read from Control Register

### 7.5.4 Control Register

Following the successful acknowledgment of the address byte, the bus controller sends a command byte that is stored in the control register in the TCA9846 (see Figure 7-5). This register can be written and read via the I<sup>2</sup>C bus. Each bit in the command byte corresponds to a SCn/SDn channel and a high (or 1) selects this channel. Multiple SCn/SDn channels can be selected at the same time. When a channel is selected, the channel becomes active after a stop condition has been placed on the I<sup>2</sup>C bus. This makes sure that all SCn/SDn lines are in a high state when the channel is made active, so that no false conditions are generated at the time of connection. A stop condition always must occur immediately after the acknowledge cycle. If multiple bytes are received by the TCA9848, the last byte received is saved.

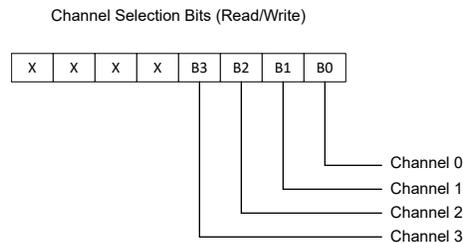


Figure 7-5. Control Register

Table 7-2 shows the TCA9846 Command Byte Definition.

**Table 7-2. Command Byte Definition**

CONTROL REGISTER BITS								COMMAND
D7	D6	D5	D4	B3	B2	B1	B0	
X	X	X	X	X	X	X	0	Channel 0 disabled
							1	Channel 0 enabled
X	X	X	X	X	X	X	0	Channel 1 disabled
							1	Channel 1 enabled
X	X	X	X	X	0	X	X	Channel 2 disabled
								1
X	X	X	X	0	X	X	X	Channel 3 disabled
								1
0	0	0	0	0	0	0	0	No channel selected, power-up/reset default state

### 7.5.5 $\overline{\text{RESET}}$ Input

The  $\overline{\text{RESET}}$  input is an active-low signal that can be used to recover from a bus-fault condition. When this signal is asserted low for a minimum of  $t_{WL}$ , the TCA9846 resets its registers and I<sup>2</sup>C state machine and deselects all channels. The  $\overline{\text{RESET}}$  input must be connected to  $V_{CC}$  through a pull-up resistor.

### 7.5.6 Power-On Reset

When power (from 0V) is applied to  $V_{DD}$ , an internal power-on reset holds the TCA9846 in a reset condition until  $V_{DD}$  has reached  $V_{POR}$ . At that point, the reset condition is released and the TCA9846 registers and I<sup>2</sup>C state machine initialize to the default states. After that,  $V_{CC}$  must be lowered to below  $V_{POR}$  and then back up to the operating voltage for a power-reset cycle.

### 7.5.7 Software Reset

The software reset call provides a mechanism to return all devices on the I<sup>2</sup>C bus to the power-up default state by issuing a specifically formatted I<sup>2</sup>C command. This operation assumes that the I<sup>2</sup>C bus is operating correctly and that no device is holding the bus in a latched or “hung” condition. The software reset sequence is defined as the following:

- The I<sup>2</sup>C controller issues a START condition.
- The controller transmits the reserved General Call address '0000 000' with the R/W bit set to 0 (write).
- A device acknowledges only when the device detects the full General Call address 0000 0000 (00h). If the R/W bit is set to 1 (read), no acknowledge is generated.
- After the General Call address is acknowledged, the controller transmits a single data byte with the value 06h.
  - The device acknowledges only when this data byte is equal to 06h.
  - If the data byte is not 06h, or if more than one data byte is transmitted, the device does not acknowledge further.
  - When the correct byte has been received and acknowledged, the controller must issue a STOP condition to complete the Software Reset sequence. At this point, the device resets the registers to the power-up default values and becomes ready for subsequent bus transactions after the required bus-free time.
  - If a Repeated START condition is issued instead of a STOP, the reset is not performed.
  - Any missing acknowledge from the device at any point in this sequence is treated by the controller as a Software Reset Abort. In such a case, the device does not initiate any register reset.

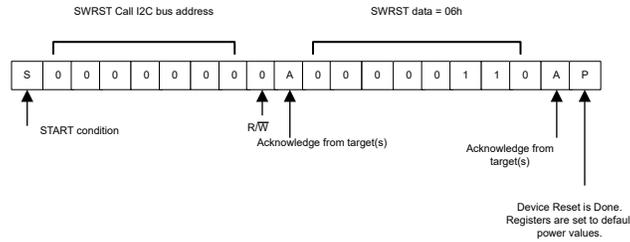


Figure 7-6. Software Reset Sequence

### 7.5.8 Device ID

The Device ID is a 24-bit (3-byte) read-only value containing the following fields:

- 12 bits: manufacturer identifier (unique per manufacturer, for example, TI)
- 9 bits: part number (assigned by the manufacturer)
- 3 bits: die revision (assigned by the manufacturer)

The Device ID is hardwired and accessible using the following procedure:

1. Send a START command.
2. The controller transmits the Reserved Device ID I<sup>2</sup>C address (1111 1000) with R/W = 0 (write).
3. The controller sends the target device address, with the LSB as “don’t care.” Only the matching device acknowledges.
4. Issue a Repeated START condition.
  - a. A STOP command followed by a START command resets the target state machine and the Device ID read cannot be performed. Also, a STOP command or a Re-START command followed by an access to another target device resets the target state machine and the Device ID Read cannot be performed.
5. The controller sends the Reserved Device ID I<sup>2</sup>C address (1111 1001) with R/W = 1 (read).
6. The device transmits the Device ID in the following order:
  - a. First byte + 4 MSBs of second byte: Manufacturer ID (12 bits)
  - b. 4 LSBs of second byte + 5 MSBs of third byte: Part Identification (9 bits)
  - c. 3 LSBs of third byte: Die Revision (3 bits)
7. The controller completes the read by sending a NACK after the last byte, resetting the device internal state machine and then issuing a STOP command.

If the controller sends additional acknowledgments after the third byte, the device restarts the data sequence from the first byte.

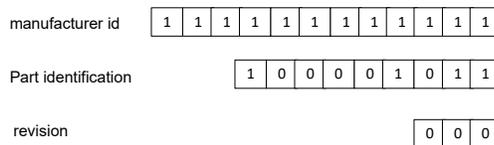
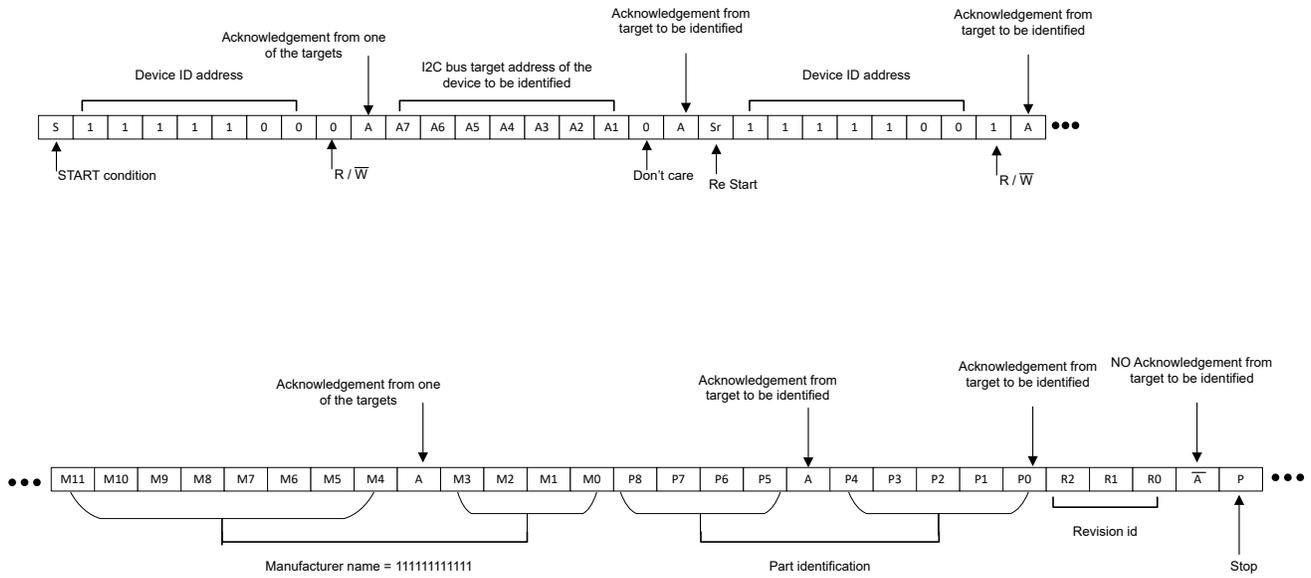


Figure 7-7. Device ID



If more than 3 bytes are read, the target device loops back to the first byte (manufacturer byte) and keeps sending data until the controller generates a 'no acknowledge'.

**Figure 7-8. Device ID Sequence**

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

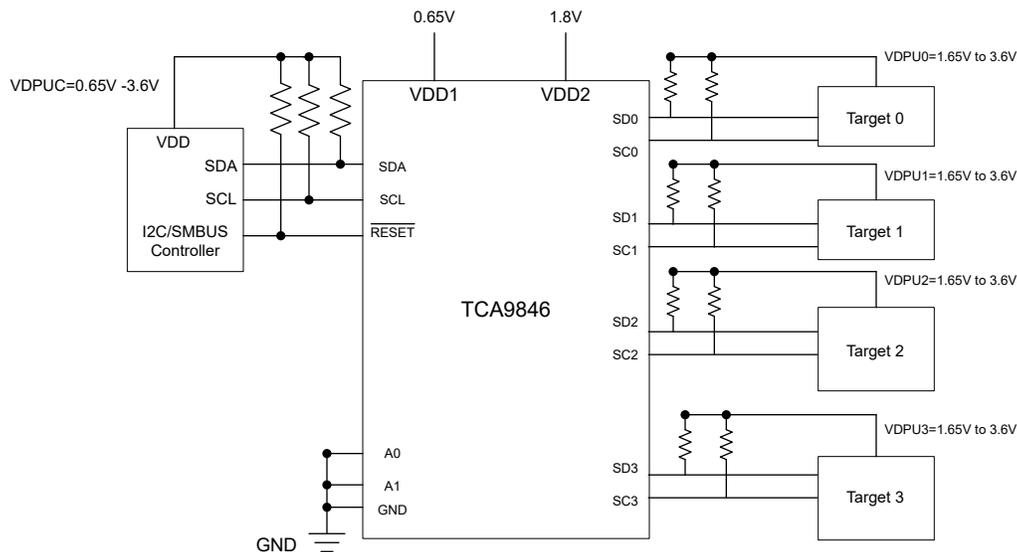
### 8.1 Application Information

Applications of the TCA9846 contain an I<sup>2</sup>C (or SMBus) controller device and up to eight I<sup>2</sup>C target devices. The downstream channels are used to resolve I<sup>2</sup>C target address conflicts. For example, if 4 identical digital temperature sensors are needed in the application, one sensor can be connected at each channel: 0-3. When the temperature at a specific location is read, the appropriate channel can be enabled and all other channels switched off, the data can be retrieved, and the I<sup>2</sup>C controller can move on and read the next channel.

In an application where the I<sup>2</sup>C bus contains many additional target devices that do not result in I<sup>2</sup>C target address conflicts, these target devices can be connected to any desired channel to distribute the total bus capacitance across multiple channels. If multiple switches are enabled simultaneously, additional design requirements must be considered (see the [Design Requirements](#) section and [Detailed Design Procedure](#) section).

### 8.2 Typical Application

Figure 8-1 shows an application in which the TCA9846 can be used.



**Figure 8-1. Typical Application Schematic**

### 8.2.1 Design Requirements

A typical application of the TCA9846 contains one or more data pull-up voltages,  $V_{DPUX}$ , one for the controller device ( $V_{DPUM}$ ) and one for each of the selectable target channels ( $V_{DPU0} - V_{DPU7}$ ). In the event where the controller device and all target devices operate at the same voltage, then  $V_{DPUM} = V_{DPUX} = V_{CC}$ . In an application where voltage translation is necessary, additional design requirements must be considered to determine an appropriate  $V_{CC}$  voltage.

The A0, A1 pins are hardware selectable to control the target address of the TCA9846. These pins can be tied directly to GND or  $V_{CC}$  in the application.

If multiple target channels are activated simultaneously in the application, then the total  $I_{OL}$  from SCL/SDA to GND on the controller side is the sum of the currents through all pull-up resistors,  $R_p$ .

The pass-gate transistors of the TCA9846 are constructed such that the  $V_{CC}$  voltage can be used to limit the maximum voltage that is passed from one I<sup>2</sup>C bus to another.

For the TCA9846 to act as a voltage translator, the  $V_{pass}$  voltage must be equal to or lower than the lowest bus voltage.

#### 8.2.1.1 Voltage Translation Requirements

UPSTREAM BUS VOLTAGE OR CONTROLLER PULLUP RESISTOR VOLTAGE $V_{DPUX}$	TCA98xx VDD1 SUPPLY VOLTAGE	CHANNEL PASS TRANSISTOR CLAMP VOLTAGE	TCA98xx VDD2 SUPPLY VOLTAGE	LOWEST DOWNSTREAM BUS VOLTAGE $V_{DPUx}$	COMMENTS
0.65	0.65	0.65	1.65-3.6	0.65-3.6	OK
1.8-3.6	0.65	0.65	1.65-3.6	0.65	OK
1.8	1.8	1.8	1.8-3.6	1.8-3.6	OK
2.5	2.5	1.8	1.8	1.8	OK
2.5	2.5	2.5	2.3-3.6	2.3-3.6	OK
3.6	3.6	1.8	1.8	1.8	OK
3.6	3.6	2.5	2.5	2.5	OK
3.6	3.6	3.6	3.6	3.6	OK
1.8	1.8	1.8	1.8	0.65	NOT OK
2.5	2.5	1.8	1.8	0.65	NOT OK
3.6	3.6	1.8	1.8	0.65	NOT OK

There is no buffering capability between the upstream and the downstream buses. This is simply a pass transistor, which acts like a multiplexer and a series resistor, between these bus segments.

### 8.2.2 Detailed Design Procedure

Once all the targets are assigned to the appropriate target channels and bus voltages are identified, the pull-up resistors,  $R_p$ , for each of the buses need to be selected appropriately. The minimum pullup resistance is a function of  $V_{DPUX}$ ,  $V_{OL(max)}$ , and  $I_{OL}$  as shown in [Equation 1](#):

$$R_{p(min)} = \frac{V_{DPUX} - V_{OL(max)}}{I_{OL}} \quad (1)$$

The maximum pullup resistance is a function of the maximum rise time,  $t_r$  (300ns for fast-mode operation,  $f_{SCL} = 400kHz$ ) and bus capacitance,  $C_b$  as shown in [Equation 2](#):

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \quad (2)$$

The maximum bus capacitance for an I<sup>2</sup>C bus must not exceed 400pF for fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the TCA9846, C<sub>io(OFF)</sub>, the capacitance of wires, connections and traces, and the capacitance of each individual target on a given channel. If multiple channels are activated simultaneously, each of the targets on all channels contribute to total bus capacitance.

### 8.3 Power Supply Recommendations

The operating power-supply voltage range of the TCA9846 is 0.65V to 3.6V for VDD1 and 1.65-3.6V for VDD2. Whenever the TCA9846 is powered on, the device executes a power-on reset. Make sure the power supply sequencing follows the power-on reset requirements in the following section. The power-on reset requirements must be followed to make sure the I<sup>2</sup>C bus logic is initialized properly.

#### 8.3.1 Power-On Reset Requirements

In the event of a glitch or data corruption, TCA9846 can be reset to the default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

A power-on reset is shown in Figure 8-2.

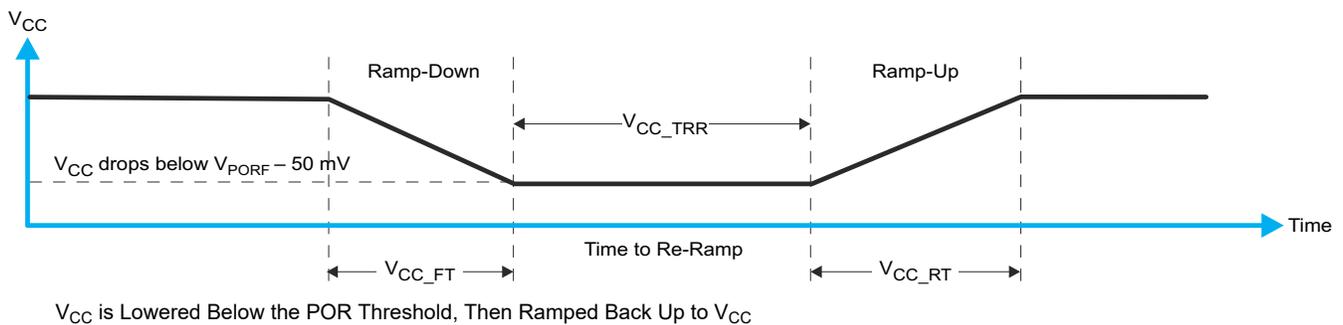


Figure 8-2. Power-On Reset Waveform

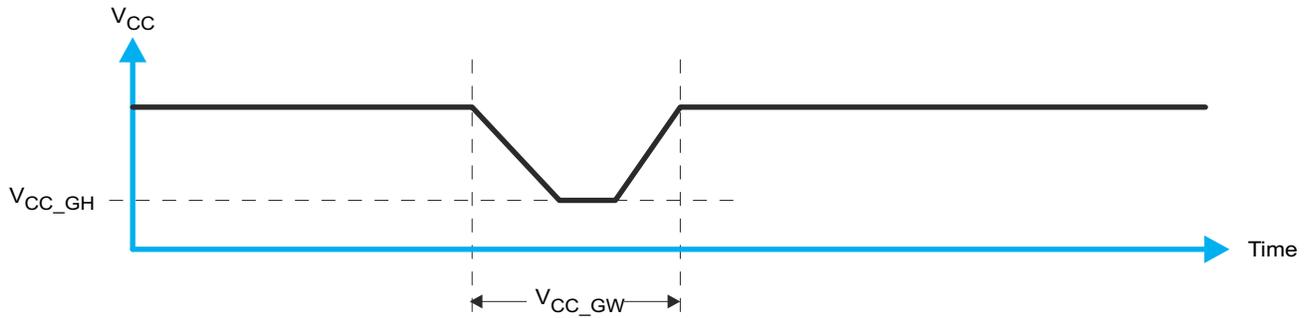
Table 8-1 specifies the performance of the power-on reset feature for TCA9846 for both types of power-on reset.

Table 8-1. Recommended Supply Sequencing and Ramp Rates

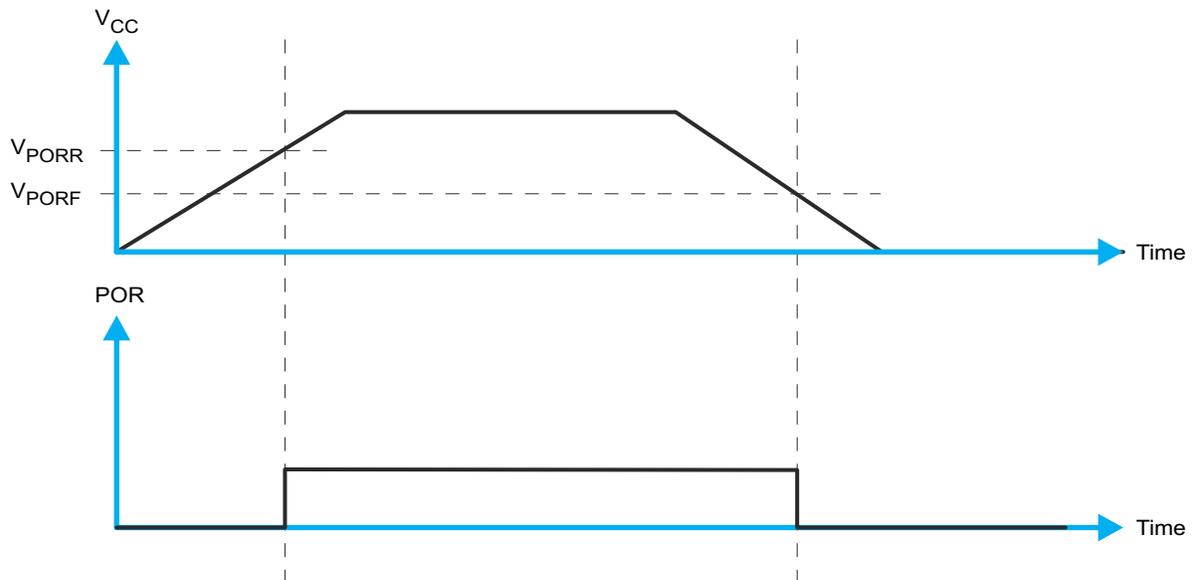
PARAMETER <sup>(1)</sup>		MIN	MAX	UNIT
V <sub>CC_FT</sub>	Fall time	0.1	2000	ms
V <sub>CC_RT</sub>	Rise time	0.1	2000	ms
V <sub>CC_TRR</sub>	Time to re-ramp (when V <sub>CC</sub> drops below V <sub>PORF(min)</sub> – 50mV or when V <sub>CC</sub> drops to GND)	10		µs
V <sub>CC_GH</sub>	Level that V <sub>CC</sub> can glitch down to, but not cause a functional disruption when V <sub>CC_GW</sub> = 1µs		1	V
V <sub>CC_GW</sub>	Glitch width that does not cause a functional disruption when V <sub>CC_GH</sub> = 0.5 × V <sub>CC</sub>		10	µs

(1) All supply sequencing and ramp rate values are measured at T<sub>A</sub> = 25°C

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width (V<sub>CC\_GW</sub>) and height (V<sub>CC\_GH</sub>) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. Figure 8-3 and Table 8-1 provide more information on how to measure these specifications.


**Figure 8-3. Glitch Width and Glitch Height**

$V_{POR}$  is critical to the power-on reset.  $V_{POR}$  is the voltage level at which the reset condition is released and all the registers and the I<sup>2</sup>C/SMBus state machine are initialized to the default states. The value of  $V_{POR}$  differs based on the  $V_{CC}$  being lowered to or from 0. Figure 8-4 and Table 8-1 provide more details on this specification.


**Figure 8-4.  $V_{POR}$** 

## 8.4 Layout

### 8.4.1 Layout Guidelines

For PCB layout of the TCA9846, common PCB layout practices must be followed but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I<sup>2</sup>C signal speeds. Having a dedicated ground plane on an inner layer of the board is common, and pins that are connected to ground must have a low-impedance path to the ground plane in the form of wide polygon pours and multiple vias. Bypass and decoupling capacitors are commonly used to control the voltage on the VCC pin, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple.

In an application where voltage translation is not required, all  $V_{DPUX}$  voltages and  $V_{CC}$  can be at the same potential and a single copper plane can connect all of pull-up resistors to the appropriate reference voltage. In an application where voltage translation is required,  $V_{DPUM}$  and  $V_{DPU0} - V_{DPU7}$ , can all be on the same layer of the board with split planes to isolate different voltage potentials.

To reduce the total I<sup>2</sup>C bus capacitance added by PCB parasitics, data lines (SCn and SDn) must be as short as possible and the widths of the traces must also be minimized (for example, 5-10 mils depending on copper weight).

### 8.4.2 Layout Example

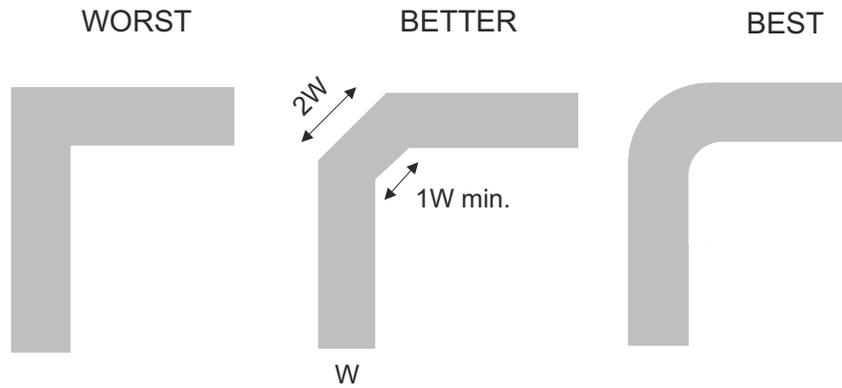


Figure 8-5. Layout Schematic

## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [I2C Bus Pullup Resistor Calculation](#) application note
- Texas Instruments, [Maximum Clock Frequency of I2C Bus Using Repeaters](#) application note
- Texas Instruments, [Introduction to Logic](#) application note
- Texas Instruments, [Understanding the I2C Bus](#) application note
- Texas Instruments, [Choosing the Correct I2C Device for New Designs](#) application note
- Texas Instruments, [TCA9548AEVM user's guide](#)

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision * (March 2026) to Revision A (May 2026)</b>	<b>Page</b>
• Updated the table note in the <a href="#">Absolute Maximum Ratings</a> table to current standards.....	4
• Updated the CDM row in the <a href="#">ESD Ratings</a> table to show testing is per ANSI/ESDA/JEDEC JS-002.....	4
• Deleted the first <i>Electrical Characteristics</i> table from the document.....	4
• Changed I <sub>OL</sub> MIN from 15 to 20 in the <a href="#">Electrical Characteristics (Global)</a> table.....	4
• Changed all instances of legacy terminology to controller and target where I2C is mentioned.....	11
• Updated the number of channels in the <i>Control Register</i> section.....	17
• Added the <i>Software Reset</i> section.....	18
• Added the <i>Device ID</i> section.....	19
• Updated <a href="#">Figure 8-1</a> with the latest device information.....	21
• Added the <i>Voltage Translation Requirements</i> section.....	22
• Updated the MIN and MAX values in <a href="#">Table 8-1</a> .....	23
• Updated <a href="#">Figure 8-5</a> with the latest device information.....	25

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## Package Option Addendum

### PACKAGING INFORMATION

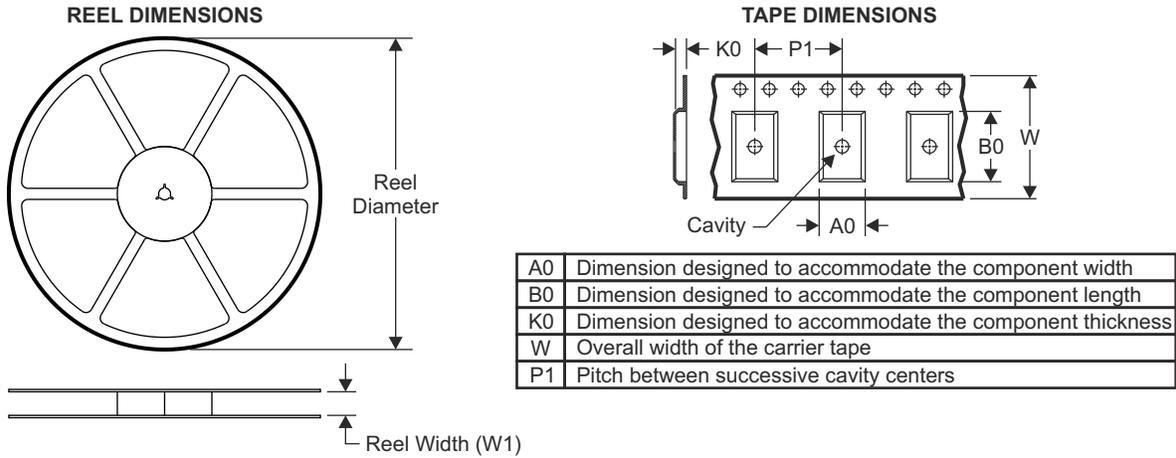
Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/Ball material (4)	MSL rating/Peak reflow (5)	Op temp (°C)	Part marking (6)
TCA9846PWR	Active	PRE_PROD	TSSOP (PW)   16					-40 to 125	
TCA9846RUMR	Active	PRE_PROD	WQFN(RUM)  16					-40 to 125	

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part. Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

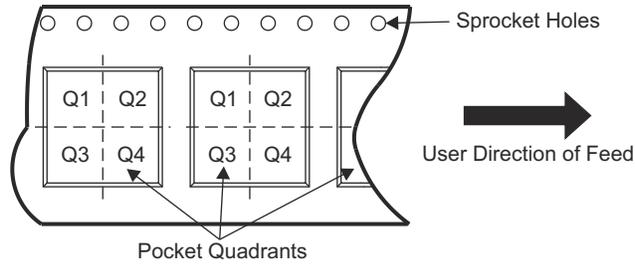
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### 11.1 Tape and Reel Information



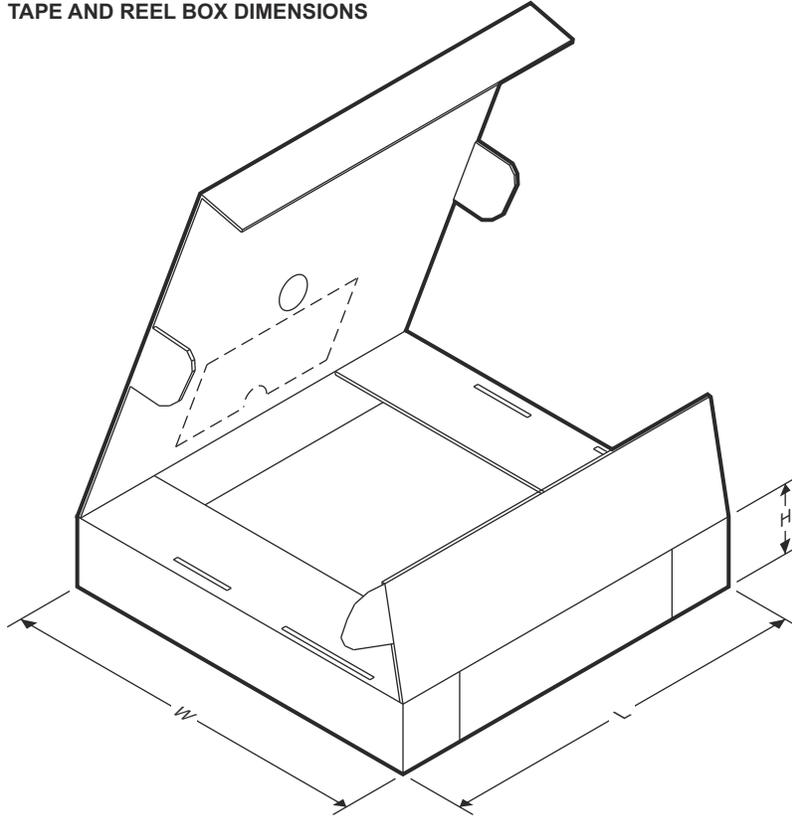
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9846PW	TSSOP	PW	16	3000	330	12.4	6.90	5.60	1.60	8	12	Q1
TCA9846RUM	WQFN	RUM	16	3000	330	12.4	4.25	4.25	1.15	8	12	Q2

**ADVANCE INFORMATION**

**TAPE AND REEL BOX DIMENSIONS**

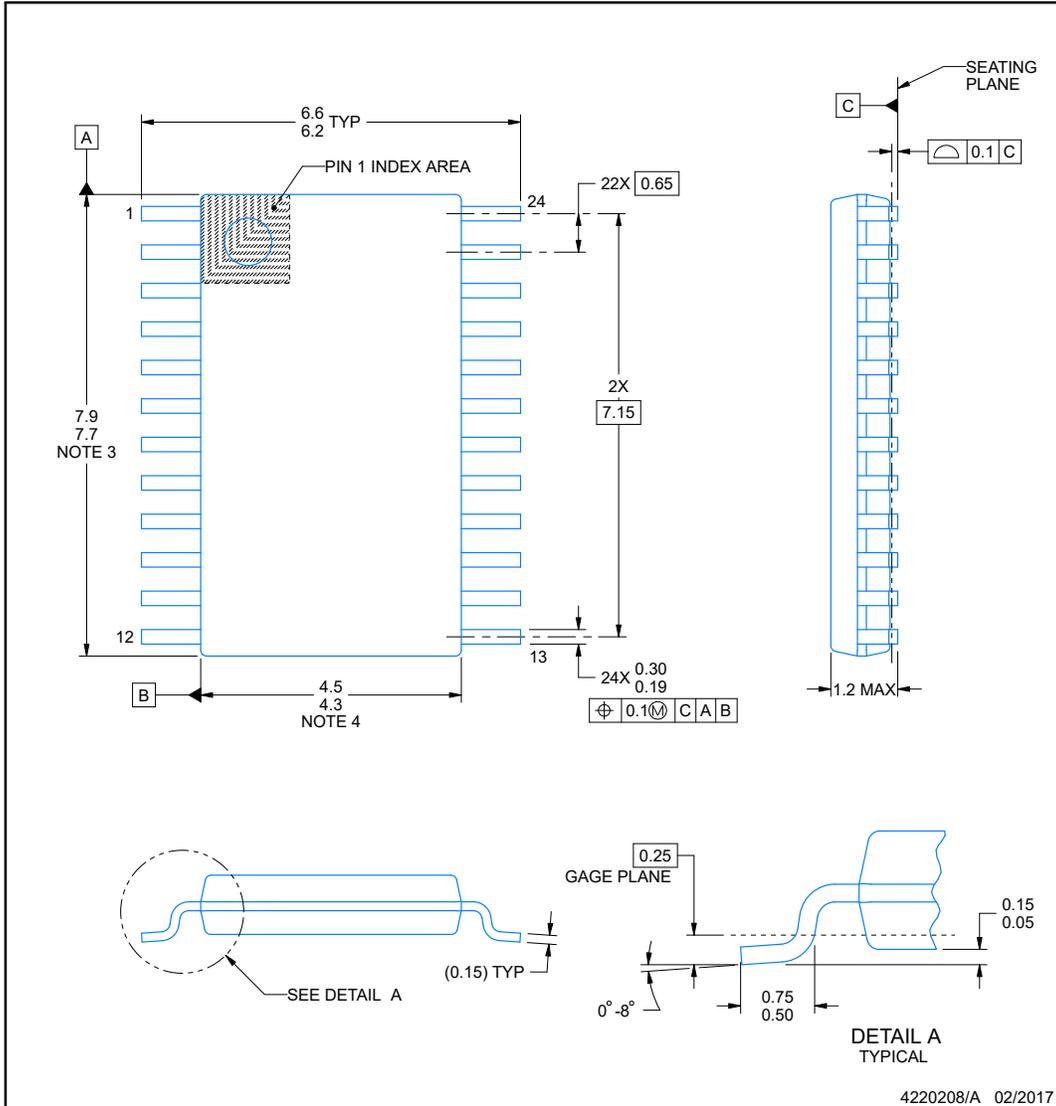


Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9846PWR	TSSOP	PW	16	3000	346	346	33
TCA9846RUMR	WQFN	RUM	16	3000	346	346	33

**ADVANCE INFORMATION**

**11.2 Mechanical Data**

**PW0024A**  **PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**  
SMALL OUTLINE PACKAGE



**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

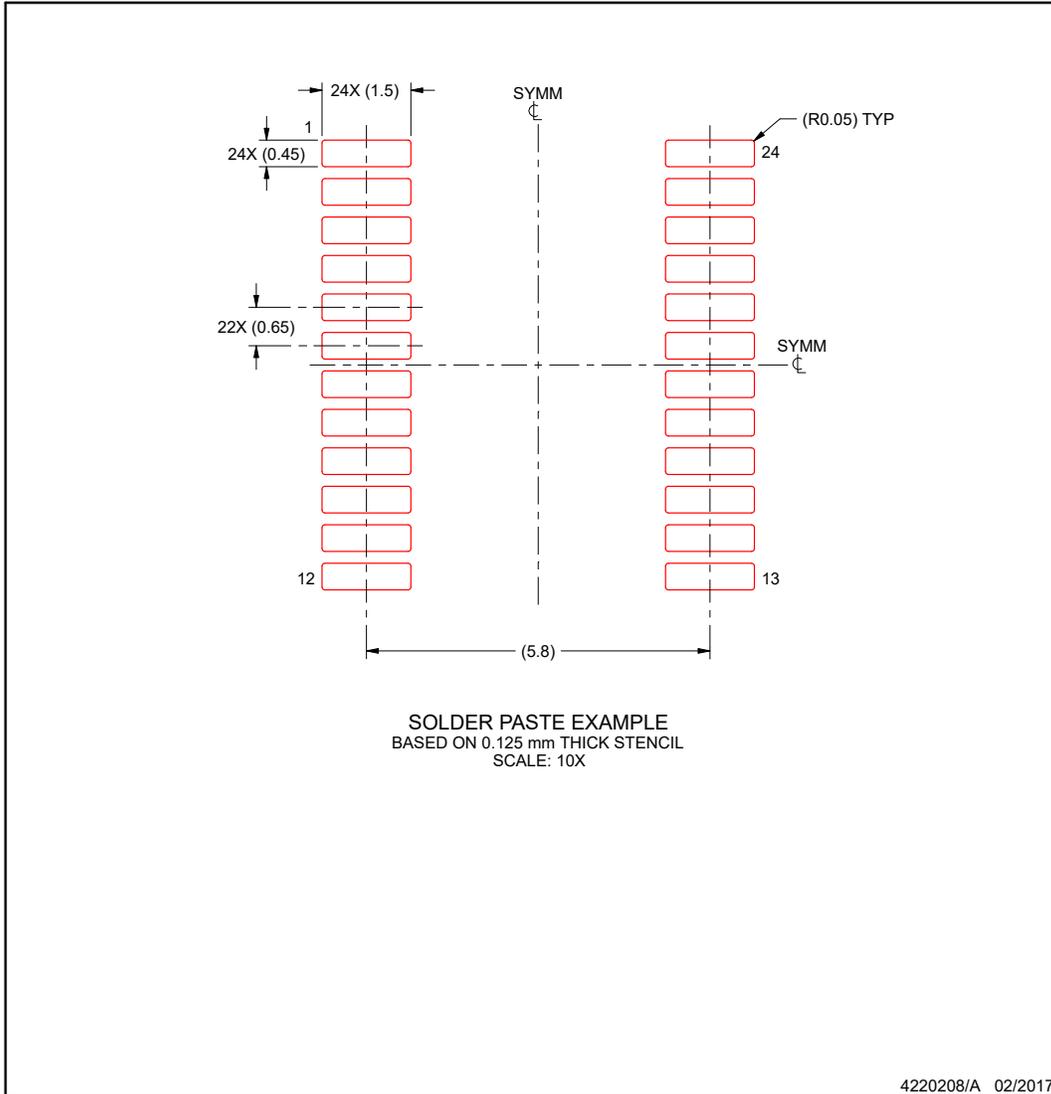


**EXAMPLE STENCIL DESIGN**

**PW0024A**

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.

**ADVANCE INFORMATION**

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">PTCA9846PWR</a>	Active	Preproduction	TSSOP (PW)   16	3000   LARGE T&R	-	Call TI	Call TI	-40 to 125	

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

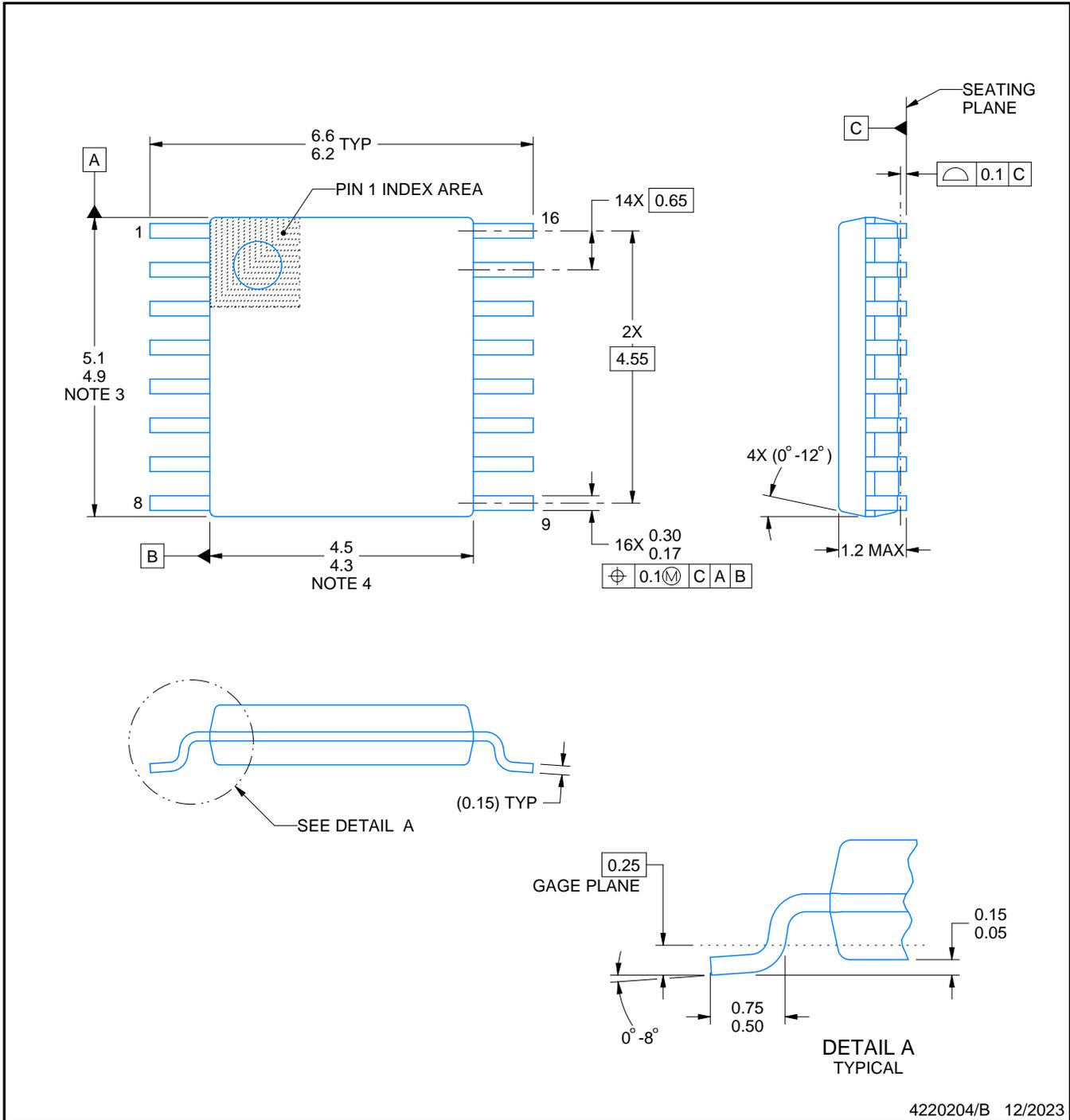
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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NOTES:

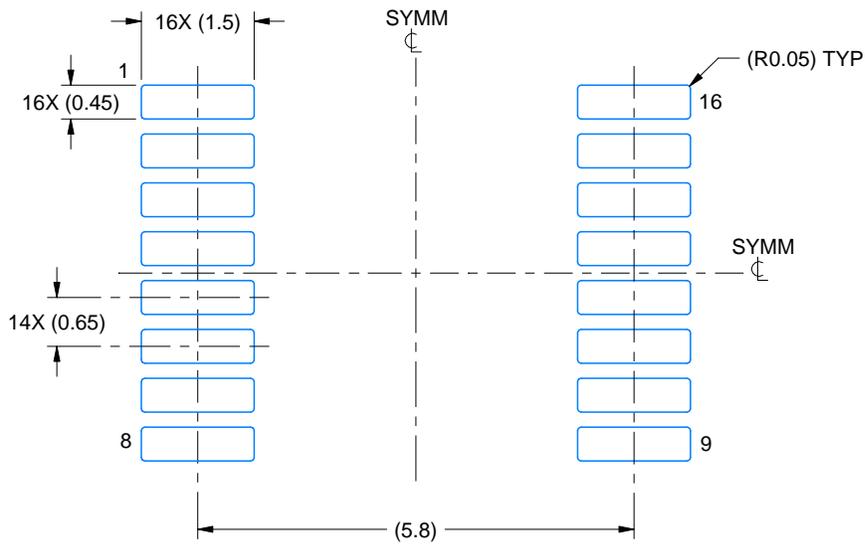
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

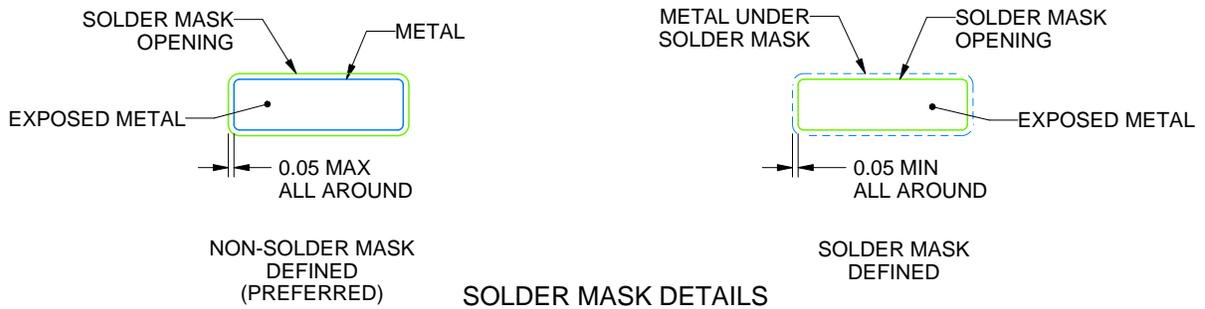
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

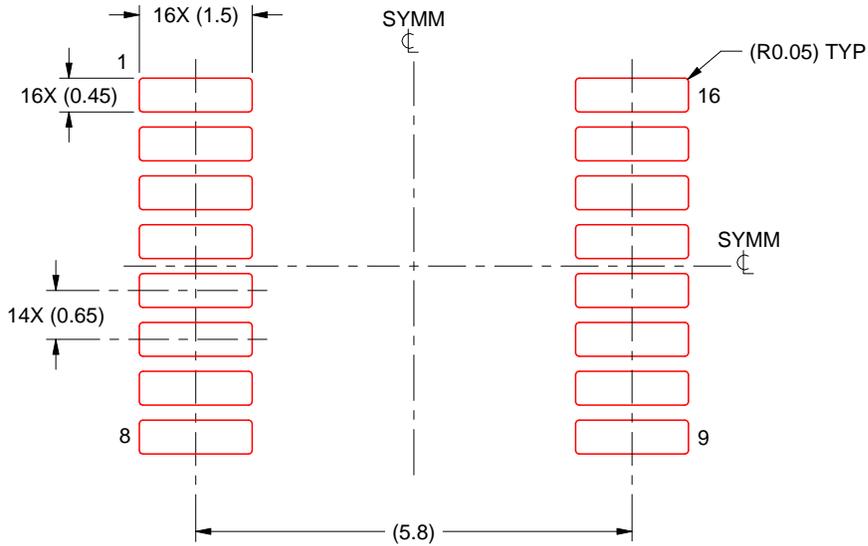
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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